

DM-TFT40-445

**4.0" IPS 720 X 720 TFT LCD TRANSMISSIVE
DISPLAY PANEL - SPI, RGB**

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1 Revision History

Date	Changes
2022-06-29	First release

2 Main Features

Item	Specification	Unit
Resolution	720(RGB)*720	pixel
Display area(AA)	71.928(H)*71.928(V) (4.0 inch)	mm
Module Dimension	77(H) x 80(V) x 2.6(D)	mm
TFT Controller IC	NV3052C	-
Interface	3SPI+16/18/24 bit RGB	-
Dot Pitch	0.0999(H)*0.0999(V)	mm
Display Color	16.7M	colors
View Direction	ALL	o'clock
Display mode	Transmissive /Normally Black	
Operating temperature	-30~+80	°C
Storage temperature	-30~+85	°C
Weight	30	g

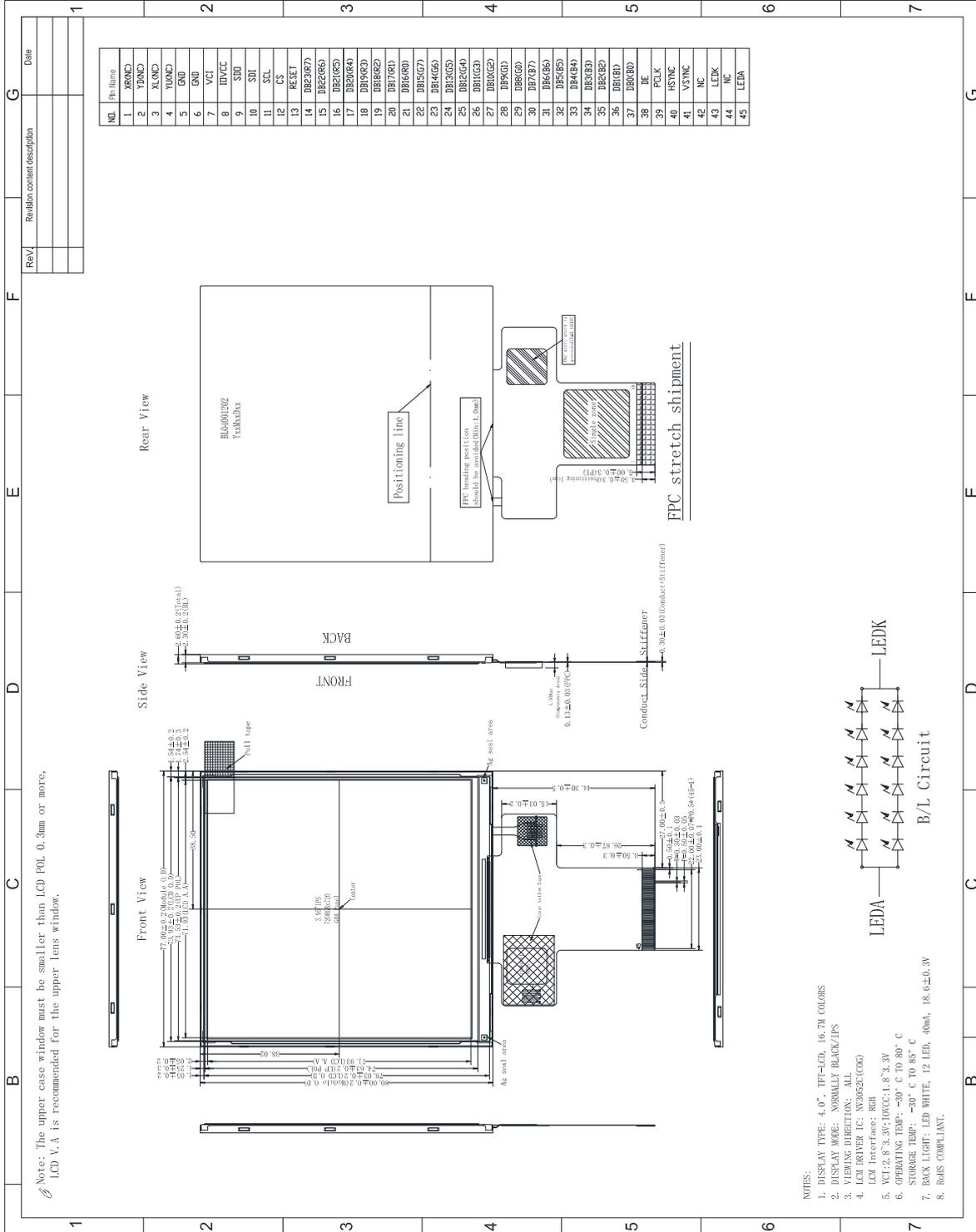
3 Pin Description

3.1 TFT

No.	Symbol	Description
1	XR(NC)	
2	YD(NC)	
3	XL(NC)	
4	YU(NC)	
5	GND	Ground
6	GND	Ground
7	VCI	Supply voltage (3.3V)
8	IOVCC	Supply voltage (Logic)(1.8~3.3V).
9	SDO	Serial data output pin used for the SPI Interface. Leave the pin to open when not in use.
10	SDI	SDI: Serial data input/output bidirectional pin for SPI Interface.
11	SCL	Serial clock input for SPI Interface.
12	CS	- A chip select signal Low: the chip is selected and accessible

		High: the chip is not selected and not accessible
13	RESET	- The external reset input - Initializes the chip with a low input. Be sure to execute a power-on reset after supplying power.
14-37	DB23-DB0	24-bit parallel data bus for RGB Interface. Fix to IOVCC or GND level when not in use.
38	DE	Data enable signal for RGB interface operation Low: access enabled High: access inhibited Fix to IOVCC or GND level when not in use.
39	PCLK	Dot clock signal for RGB interface operation.
40	HSYNC	Line synchronizing signal for RGB interface operation.
41	VSYNC	Frame synchronizing signal for RGB interface operation.
42	NC	--
43	LEDK	Cathode pin of backlight.
44	NC	--
45	LEDA	Anode pin of backlight.

4 Mechanical Drawing



5 Electrical Characteristics

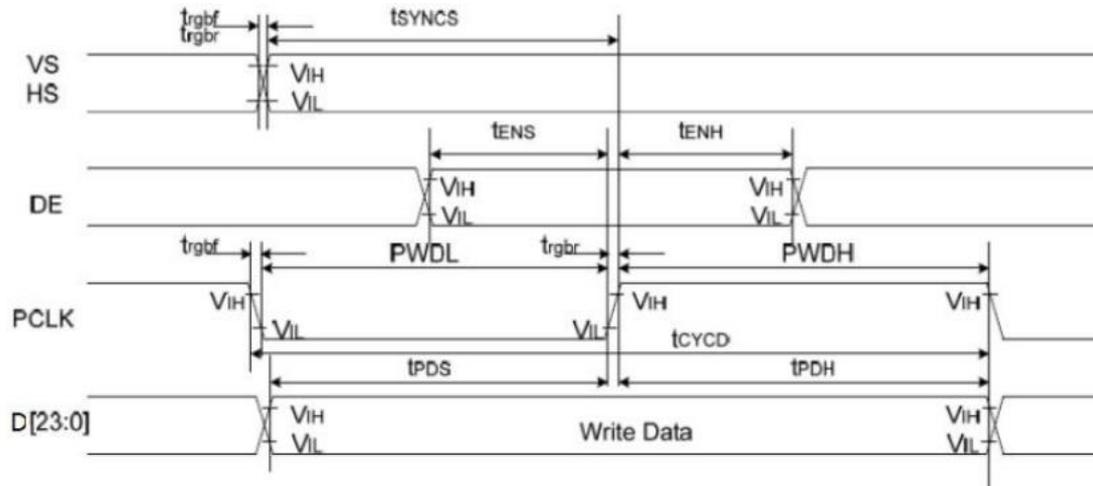
Item		Symbol	Min	Typ.	Max	Unit
Digital Supply Voltage	Absolute Maximum Rating	V _{CI}	-0.3		6.6	V
Digital interface supply Voltage	Absolute Maximum Rating	IOVCC	-0.3		4.5	V
Operating Temperature	Absolute Maximum Rating	TOP	-30		+80	°C
Storage Temperature	Absolute Maximum Rating	TST	-30		+85	°C
Digital Supply Voltage		V _{CI}	2.5	3.3	3.6	V
Digital interface supply Voltage		IOVCC	1.65	1.8	3.6	V
Normal mode Current		IDD	--	28	56	mA
Level input voltage		V _{IH}	0.7*IOVCC	--	IOVCC	V
		V _{IL}	GND	--	0.3*IOVCC	V
Level output voltage		V _{OH}	0.8*IOVCC	--	IOVCC	V
		V _{OL}	GND	--	0.2*IOVCC	V

6 Optical Characteristics

Item	Symbol	Min	Typ	Max	Unit
Forward Current	I _F	--	40	-	mA
Forward Voltage	V _F	--	18.6	-	V
LCM Luminance	LV	650	700	-	cd/m ²
LED life time	H _r	--	50000	-	Hour
Uniformity	Avg	80	--	-	%

7 AC Characteristics

7.1 Parallel 24/18/16-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter	min	max	Unit	Description
VS/HS	tSYNCS	VS/HS setup time	5	-	ns	24/18/16-bit bus RGB interface mode
	tSYNCH	VS/HS hold time	5	-	ns	
DE	tENS	DE setup time	5	-	ns	
	tENH	DE hold time	5	-	ns	
D[23:0]	tPOS	Data setup time	5	-	ns	
	tPDH	Data hold time	5	-	ns	
PCLK	PWDH	PCLK high-level period	13	-	ns	
	PWDL	PCLK low-level period	13	-	ns	
	tCYCD	PCLK cycle time	28	-	ns	
	trgbf, trgbr	PCLK, HS, VS rise/fall time	-	15	ns	

7.2 Serial interface characteristics

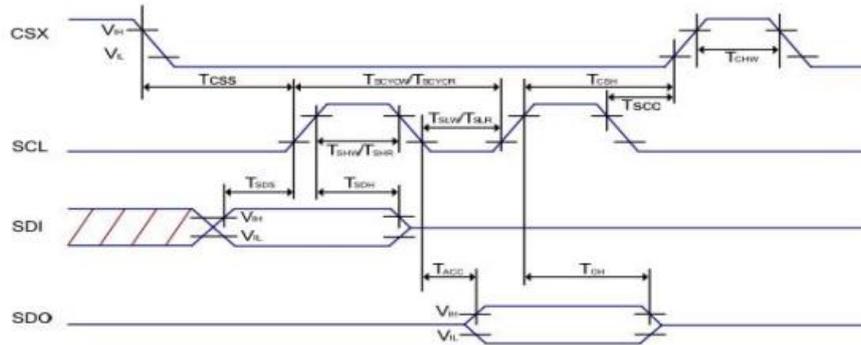


Figure: 3-pin Serial Interface Characteristics

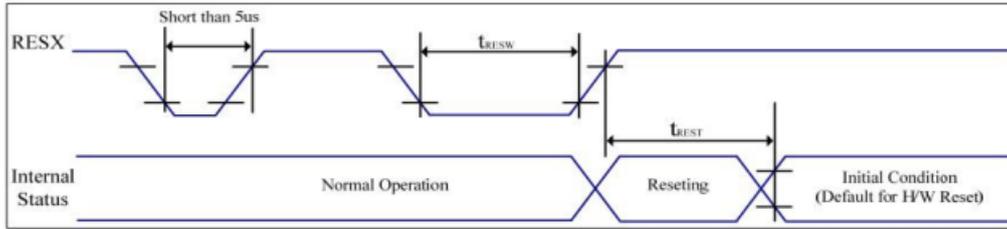
Table: SPI Interface Characteristics

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	T_{CSS}	Chip select setup time	15	-	ns	-
	T_{CSH}	Chip select hold time	15	-	ns	
	T_{SCC}	Chip select setup time	20	-	ns	
	T_{CHW}	Chip "H" pulse width	40	-	ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66	-	ns	-
	T_{SHW}	SCL "H" pulse width (Write)	10	-	ns	
	T_{SLW}	SCL "L" pulse width (Write)	10	-	ns	
	T_{SCYCR}	Serial clock cycle (Read)	150	-	ns	-
	T_{SHR}	SCL "H" pulse width (Read)	60	-	ns	
T_{SLR}	SCL "L" pulse width (Read)	60	-	ns		
SDI	T_{SDS}	Data setup time	10	-	ns	-
	T_{SDH}	Data hold time	10	-	ns	
	T_{ACC}	Access time	10	50	ns	For maximum $C_L=30\text{pF}$ For minimum $C_L=8\text{pF}$
	T_{OH}	Output disable time	15	50	ns	

Note 1: IOVCC=1.65 to 3.6V, VCI=2.5 to 6V, VSSA=VSS=0V

Note 2: The rise time and fall time (t_r , t_f) of input signal is specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

7.3 Reset Timing



Symbol	Parameter	Related Pins	MIN	TYP	MAX	Note	Unit
t_{RESW}	*1) Reset low pulse width	RESX	10	-	-	-	us
t_{REST}	*2) Reset complete time	-	-	-	5	When reset applied during Sleep in mode	ms
		-	-	-	120	When reset applied during Sleep out mode	ms

Table: Reset input timing

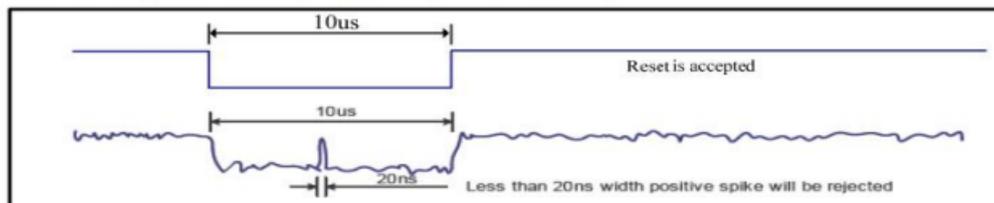
Note 1: Due to an electrostatic discharge on RESX line, spike does not cause irregular system reset according to the table below.

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts (It depends on voltage and temperature condition.)

Note 2: During the resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120ms, when Reset Starts in Sleep Out mode. The display remains the blank state in Sleep In mode), then return to default condition for H/W reset.

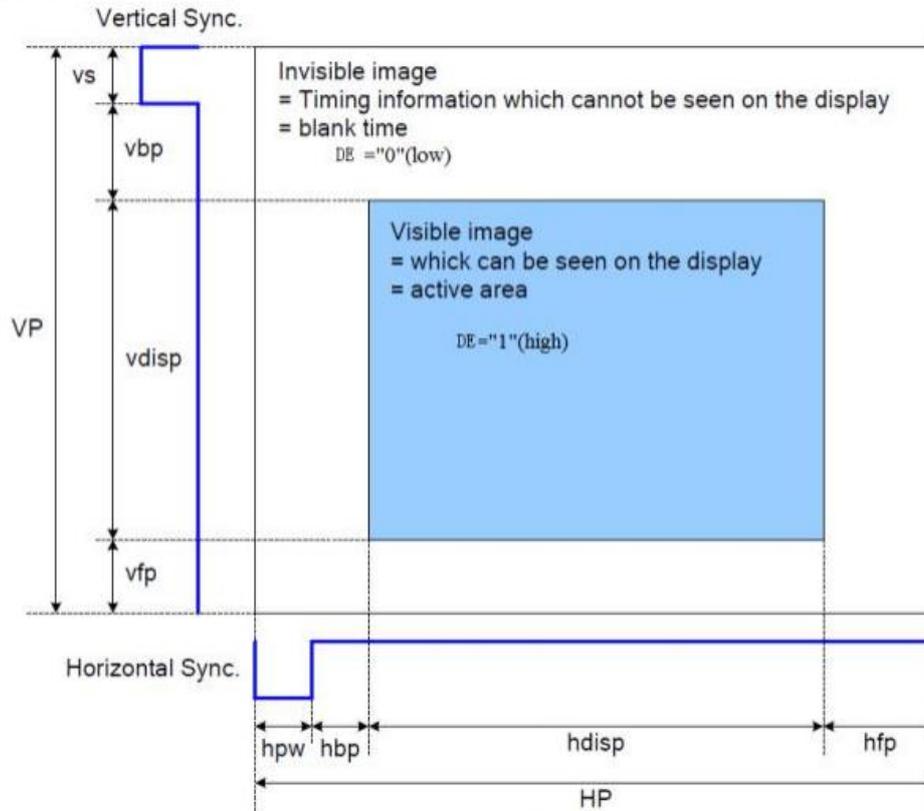
Note 3: During Reset Complete Time, ID1/ID2/ID3 and VCOM value in OTP will be latched to internal register. After a rising edge of RESX, there is a H/W reset complete time (t_{REST}) which lasted 5ms. The loading operation will be done every time during this reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:



Note 5: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120 msec.

D[23:0] are used to tell what is the information of the image that is transferred on the display(When DE= '0' (low) and there is a rising edge of PCLK). D[23:0] can be '0' (low) or '1'(high). These lines are read by a rising edge of the PCLK signal.



DRAM Access Area by RGB Interface

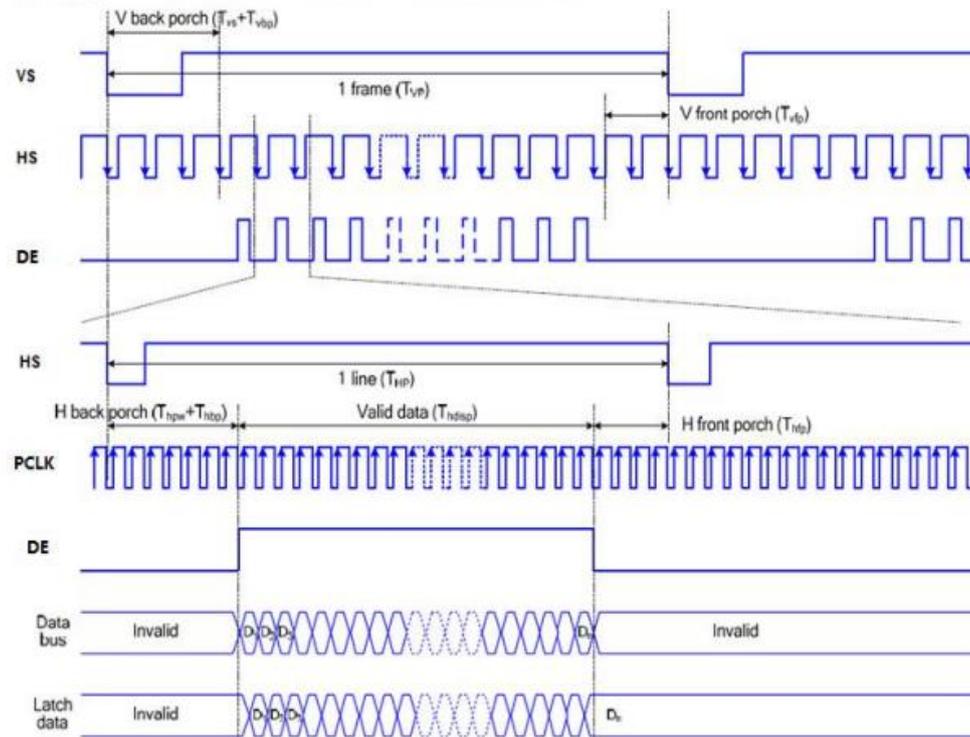
8.1 RGB Interface Mode Selection

NV3052CGRB supports two kinds of RGB interface, DE mode and SYNC mode. The table shown below uses command 23h to select RGB interface mode.

sync_mode[1:0]	RGB Mode
00	SYNC+DE mode
01	SYNC mode
10	DE mode
11	SYNC+DE mode

8.2 RGB Interface Timing

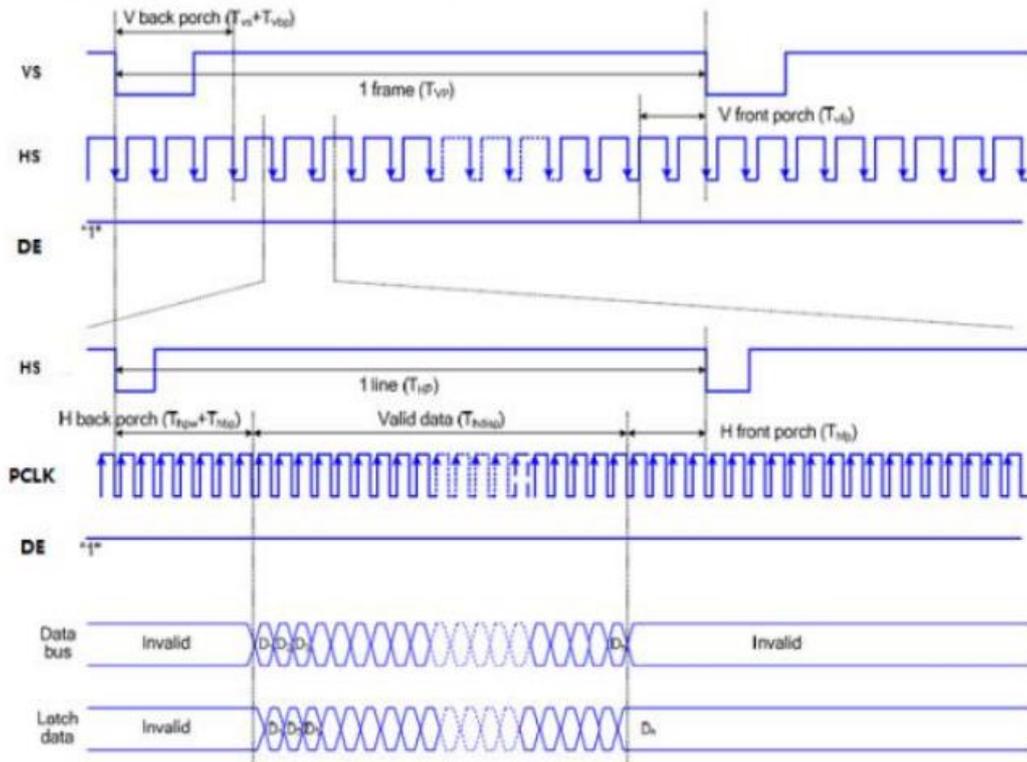
The timing chart of RGB interface DE mode is shown as follows.



Timing Chart of Signals in RGB Interface DE Mode

Note: The setting of front porch and back porch in host must match that in IC as this mode.

The timing chart of RGB interface SYNC mode is shown as follows.



Timing chart of RGB interface SYNC mode

Please refer to the following table for the setting limitation of RGB interface signals.

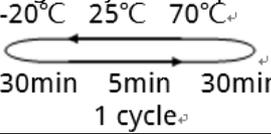
Parameter	Symbol	Min.	Typ.	Max.	Unit
DCLK frequency	FCLK	--	37	--	MHz
Horizontal Sync. Width	hpw	1	4	255	Clock
Horizontal Sync. Back Porch	hbp	1	40	255	Clock
Horizontal Sync. Front Porch	hfp	1	44	--	Clock
Vertical Sync. Width	vs	1	4	254	Line
Vertical Sync. Back Porch	vbp	1	22	254	Line
Vertical Sync. Front Porch	vfp	1	16	--	Line

Note:

1. Typical value are related to the setting frame rate is 60Hz..

9 Reliability

Test Item	Content of Test	Test Condition	Note
High Temperature Storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature Storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	-

Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max, for 96hrs under no-load condition excluding the polarizer. Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal Shock Resistance	The sample should be allowed stand the following 10 cycles of operation. 	-20°C/70°C 10 cycles	-
Vibration Test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 15mm; Vibration: 10~55Hz; One cycle 60 seconds to 3 directions of X, Y, Z, for each 16 minutes.	3
Static Electricity Test	Endurance test apply the electric stress to the terminal.	VS=800V, RS=1.5kΩ, CS=100pF, 1 time.	-

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal. Temperature and humidity after remove from the rest chamber.

Note3: Test performed on product itself, not inside a container

10 Warranty and Conditions

<http://www.displaymodule.com/pages/faq><http://www.displaymodule.com/pages/faq>